Compliant with IEC 62474/ D9.00 Compliant to IEC 61249-2-21:2003

| MICROCHIP Semiconductor Device Type: MNXIA (PEA) 032 VQFN 5x5x0.9mm NiPdAu | | | Termination Base Alloy: Copper Alloy (Cu) | | | Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays) | | | | J-STD-609A Product Marking and/or Pkg. Labeling e4 |
|---|---|--|--|--|---|--|-----------------------------------|--|---|--|
| Basic Substance | CAS Number | "Contained In" Sub-Component | % Total Weight | mg/part | ppm | 35.09 | (mg) Total | Mold Compound | % ot Total Weight | 54.74 |
| Silica, fused | 60676-86-0 | Mold Compound | 49.266 | 31.580 | 492.660 | | Silica, fused | 60676-86-0 | 90.00 | |
| Epoxy Resin | Trade Secret | Mold Compound | 2.655 | 1.702 | 26.549 | ł | Epoxy Resin | Trade Secret | 4.85 | 4 |
| Phenolic Resin | Trade Secret | Mold Compound | 2.655 | 1.702 | 26,549 | 1 | Phenolic Resin | Trade Secret | 4.85 | - |
| Carbon Black | 1333-86-4 | Mold Compound | 0.164 | 0.105 | 1,642 | | Carbon Black | 1333-86-4 | 0.30 | |
| Copper | 7440-50-8 | Lead Frame | 41.925 | 26.874 | 419,250 | 1 | Carbon Black | Total | 100.00 | 4 |
| Iron | 7439-89-6 | Lead Frame | 0.976 | 0.626 | 9,761 | 27.56 | (mg) Total | Lead Frame | % of Total Weight | 43.00 |
| Zinc | 7440-66-6 | Lead Frame | 0.052 | 0.033 | 516 | 27.56 | | 7440-50-8 | 97.50 | 43.00 |
| Phosphorous | 7723-14-0 | Lead Frame | 0.052 | 0.030 | 473 | ł | Copper | 7440-50-8 7439-89-6 | 2.27 | 4 |
| Silver | 7440-22-4 | Die Attach | 0.047 | 0.030 | 1.309 | ł | Zinc | 7439-89-6 | 0.12 | 4 |
| Acrylic Resin | Trade secret | Die Attach | 0.131 | 0.084 | 1,309 | 1 | Phosphorous | 7440-66-6 7723-14-0 | 0.12 | |
| Epoxy Resin | Trade secret | Die Attach | 0.004 | 0.003 | 43 | 1 | r Hospitorous | Total | 100.00 | 1 |
| Acrylated EP-Resin | Trade secret | Die Attach | 0.004 | 0.003 | 94 | 0.11 | (max Tatal | | | |
| | | | | 0.006 | 111 | 0.11 | (mg) Total | Die Attach | % of Total Weight | 0.17 |
| Polybutadiene derivative & Coplolymer | 9003-17-2 | Die Attach | 0.011 1.000 | 0.007 | | | Silver | 7440-22-4 | 77.00 | |
| Silicon Gold | 7440-21-3 7440-57-5 | Chip (Die) Wire Bond | 0.490 | 0.641 | 10,000 4.900 | | Acrylic Resin | Trade secret | 8.50 2.50 | 4 |
| Nickel | 7440-57-5 | Plating on external leads (pins) | 0.490 | 0.314 | 4,900 5.700 | | Epoxy Resin Acrylated EP-Resin | Trade secret Trade secret | 2.50 5.50 | 4 |
| Palladium | 7440-02-0 | Plating on external leads (pins) | 0.021 | 0.013 | 210 | Dalukutadi | | 9003-17-2 | 6.50 | 4 |
| Gold | | | | 0.006 | 90 | Polybutadie | ene derivative & Coplolymer | 9003-17-2 Total | 100.00 | 1 |
| Gold | 7440-57-5 | Plating on external leads (pins) | 0.009 100.000 | 64.100 | 1.000.000 | | | | | |
| Ì | | TOTALS: | 100.000 | 64.100 | 1,000,000 | 0.64 | Total (mg) Doped Silicon | Chip (Die) 7440-21-3 | % of Total Weight 100.00 | 1.00 |
| 0.0641 g Total Mass This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) 8 | | | | 1/65/FU (08.Ju | 0044\ d | | Dopod Cilicon | | | 4 |
| 2015/863/EU (31 March 2015) and 2002/53/EC (En | nd-of-l ife Vehicles (FI \ | , , , | | | ne 2011) and | | | Total | 100.00 |) |
| Committee on white the observe FU Direction 1 | un oi rue seuncies (Eri |) without exemption (zero) | | .,,,,,, | ne 2011) and | | | Total | 100.00 |) |
| Compliance with the above EU Directives has be | • | ') without exemption (zero) design controls, supplier declarations, and /or | analytical test | , | ne 2011) and | 0.31 | (mg) Total | Total Wire Bond | 100.00 % of Total Weight | 0.49 |
| If a chemical substance is absent from the list at Microchip Technology Incorporated's knowledge concentration of the chemical substance, if any, | een verified via internal of bove, the chemical subs e and belief as of the da , is not below the thresh | design controls, supplier declarations, and /or tance is NOT an intentional ingredient in the s te of this document, there is no credible reaso old of regulatory concern for any regulatory so | emiconductor on to believe that cheme world-wi | data. levice and, to t t the unavoida de. | he best of ble impurity | 0.31 | (mg) Total Gold | Wire Bond 7440-57-5 | % of Total Weight | 0.49 |
| If a chemical substance is absent from the list at Microchip Technology Incorporated's knowledge concentration of the chemical substance, if any, Molding compounds used by Microchip meet the | een verified via internal of bove, the chemical subs e and belief as of the da , is not below the thresh e UL94 V0 flammability s | design controls, supplier declarations, and /or tance is NOT an intentional ingredient in the s te of this document, there is no credible reaso old of regulatory concern for any regulatory so tandard for plastics. You can access the UL io | emiconductor on to believe that cheme world-wi | data. levice and, to t t the unavoida de. | he best of ble impurity | 0.31 | | Wire Bond | % of Total Weight | 0.49 |
| If a chemical substance is absent from the list at Microchip Technology Incorporated's knowledge concentration of the chemical substance, if any, Molding compounds used by Microchip meet the report at http://ul.com/globai/eng/pages/offering: The protective "tubes" in which the specific proon the outer box and certain "reels" may be mad | een verified via internal of bove, the chemical subse e and belief as of the da , is not below the thresh a UL94 V0 flammability s s/industries/chemicals/p duct is shipped are mad de from PVC plastic. | design controls, supplier declarations, and /or tance is NOT an intentional ingredient in the sate of this document, there is no credible reaso old of regulatory concern for any regulatory so tandard for plastics. You can access the UL ic olastics/ e from polyvinyl chloride (PVC) plastic. "Wind- | emiconductor on to believe that cheme world-wind family of downwenters. | data. levice and, to to to the unavoida de. atabases to obused to hold the | he best of ble impurity tain a test ne packing slip | | | Wire Bond 7440-57-5 | % of Total Weight | 0.49 |
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Au 15:13: 04/18/16